



1. THIS IS A 8 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
2. PRINTED CIRCUIT BOARD SHALL BE 1/2 OZ COPPER EXTERNAL LAYERS
1 OZ COPPER INTERNAL LAYERS
BOARD MATERIAL TO BE EXPOXY BASED FR-4.
3. SMOBC SOLDERMASK BOTH SIDES USING BLUE RESIST. IAW IPC-SM-840
4. SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED
INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
5. MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE.
ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS
DIRECTIVE 20002/95/EC
LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
6. ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
7. MINIMUM TRACE WIDTH 6 MILS/ SPACE 4 MILS

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+0.0/-0.0	PLATED	981
•	10.0	+0.0/-0.0	PLATED	20
•	28.0	+0.0/-0.0	PLATED	5
•	37.0	+0.0/-0.0	PLATED	14
•	40.0	+0.0/-0.0	PLATED	69
•	41.0	+0.0/-0.0	PLATED	14
•	65.0	+3.0/-3.0	PLATED	2
•	80.0	+3.0/-3.0	PLATED	3
•	93.0	+3.0/-3.0	PLATED	2
•	100.0	+3.0/-3.0	PLATED	4
•	155.0	+3.0/-3.0	PLATED	6
•	23.622	+2.0/-2.0	NON-PLATED	1
•	125.984	+4.0/-4.0	NON-PLATED	1
•	128.0	+3.0/-3.0	NON-PLATED	3
•	47.244x27.559	+2.0/-2.0	PLATED	1
•	47.244x27.559	+2.0/-2.0	PLATED	1
•	74.803x23.622	+3.0/-3.0	PLATED	2
•	76.0x28.0	+2.0/-2.0	PLATED	2
•	79.0x28.0	+4.0/-4.0	PLATED	2
•	33.465x19.685	+2.0/-2.0	NON-PLATED	1

NOTE: ALL VIAS to be TENTED. NO exposed copper pads on any VIAS top or bottom Except VIAS in SMT pads.